



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*


Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-03-10
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	IPD MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SMAJ40CA-TR	8HSR*TWB047C	A	ZA41	2016-03-10
	Amount	UoM	Unit type	ST ECOPACK Grade
	70.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOJ	4.3 x 2.77 x 2	2	J bend	
Comment	Package: SMA			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	8HSR*TW8047C					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.801	mg	supplier	die	Silicon (Si)	7440-21-3		0.756	mg	943820	10800
				supplier	metallization	Aluminium (Al)	7429-90-5		0.029	mg	36205	414
				supplier	metallization	Nickel (Ni)	7440-02-0		0.003	mg	3745	43
				supplier	Passivation	Silicon Oxide	7631-86-9		0.004	mg	4994	57
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.003	mg	3745	43
				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	1248	14
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.005	mg	6242	71
				supplier	alloy	Copper (Cu)	7440-50-8		26.864	mg	999516	383771
Leadframe & Clip	Copper and its alloy	26.877	mg	supplier	alloy	Zinc (Zn)	7440-66-6		0.001	mg	37	14
				supplier	alloy	Iron (Fe)	7439-89-6		0.003	mg	112	43
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.009	mg	335	129
				supplier	solder	Silver (Ag)	7440-22-4		0.071	mg	24939	1014
Soft solder	Solder	2.847	mg	supplier	solder	Tin (Sn)	7440-31-5		0.143	mg	50228	2043
				JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	2.633	mg	924833	37614
				supplier	mold compound	Amorphous Silica	7631-86-9		23.930	mg	616197	341857
Encapsulation	Other inorganic materials	38.835	mg	supplier	mold compound	Quartz	14808-60-7		7.767	mg	200000	110957
				supplier	mold compound	epoxy resin	25068-38-6		4.660	mg	119995	66571
				supplier	mold compound	phenolic resin	9003-35-4		2.330	mg	59997	33286
				supplier	mold compound	Bismuth trioxide	1304-76-3		0.027	mg	695	386
				supplier	mold compound	chlorine residue	7782-50-5		0.004	mg	103	57
				supplier	mold compound	Carbon black	1333-86-4		0.117	mg	3013	1671
Connections coating	Solder	0.640	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.640	mg	1000000	9143